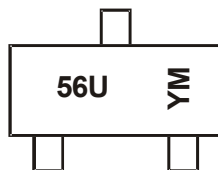


Marking Information



56U = Product Type Marking Code
 YM = Date Code Marking
 Y or Y = Year (ex: I = 2021)
 M = Month (ex: 9 = September)

Date Code Key

Year	2016	2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	D	I	J	K	L	M	N	O	P	R	S

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 6) V _{GS} = 4.5V	Steady State	T _A = +25°C T _A = +70°C	I _D	4.0 3.2	A
Maximum Body Diode Forward Current (Note 6)			I _S	1.0	A
Pulsed Drain Current (10μs pulse, duty cycle = 1%)			I _{DM}	22	A

Thermal Characteristics

Characteristic			Symbol	Value	Unit
Power Dissipation (Note 5)			P _D	0.66	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State		R _{θJA}	192	°C/W
Power Dissipation (Note 6)			P _D	0.94	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State		R _{θJA}	136	°C/W
Operating and Storage Temperature Range			T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 8V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	0.4	0.6	1.0	V	$V_{DS} = V_{GS}, I_D = 250\mu A$
Static Drain-Source On-Resistance	$R_{DS(on)}$	—	30	38	m Ω	$V_{GS} = 4.5V, I_D = 3.6A$
		—	34	45		$V_{GS} = 2.5V, I_D = 3.1A$
		—	52	85		$V_{GS} = 1.5V, I_D = 2.0A$
Diode Forward Voltage	V_{SD}	—	0.7	1.2	V	$V_{GS} = 0V, I_S = 1A$
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	339	—	pF	$V_{DS} = 10V, V_{GS} = 0V$ $f = 1.0MHz$
Output Capacitance	C_{oss}	—	47	—		
Reverse Transfer Capacitance	C_{rss}	—	34	—		
Gate Resistance	R_G	—	2.6	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge	Q_g	—	4.3	—	nC	$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 3.6A$
Gate-Source Charge	Q_{gs}	—	0.5	—		
Gate-Drain Charge	Q_{gd}	—	0.8	—		
Turn-On Delay Time	$t_{D(on)}$	—	1.8	—	ns	$V_{GS} = 4.5V, V_{DD} = 10V, R_G = 1\Omega, I_D = 3.6A$
Turn-On Rise Time	t_R	—	2.8	—		
Turn-Off Delay Time	$t_{D(off)}$	—	8.5	—		
Turn-Off Fall Time	t_F	—	1.7	—	ns	$I_F = 3.6A, dI/dt = 100A/\mu s$
Body Diode Reverse Recovery Time	t_{RR}	—	4.7	—		
Body Diode Reverse Recovery Charge	Q_{RR}	—	0.7	—	nC	$I_F = 3.6A, dI/dt = 100A/\mu s$

Notes:

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

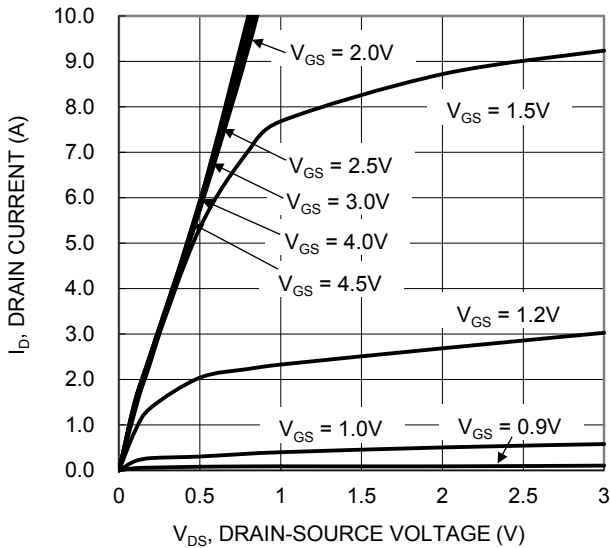


Figure 1. Typical Output Characteristic

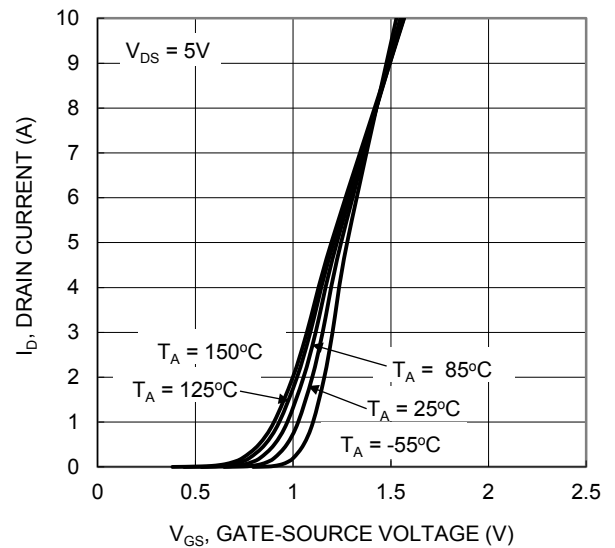


Figure 2. Typical Transfer Characteristic

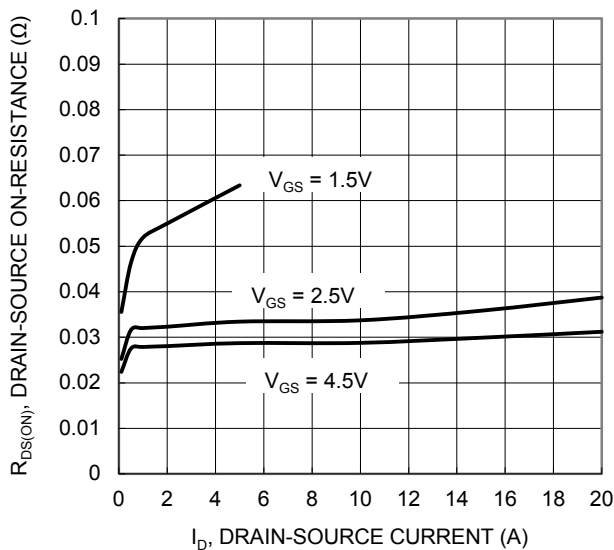


Figure 3. Typical On-Resistance vs Drain Current and Gate Voltage

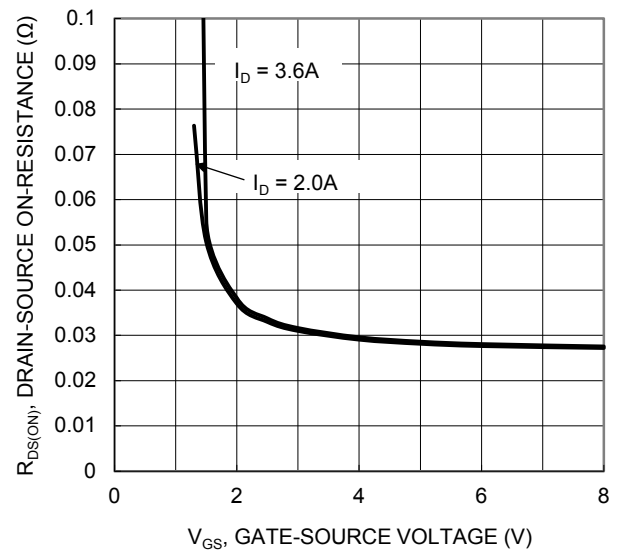


Figure 4. Typical Transfer Characteristic

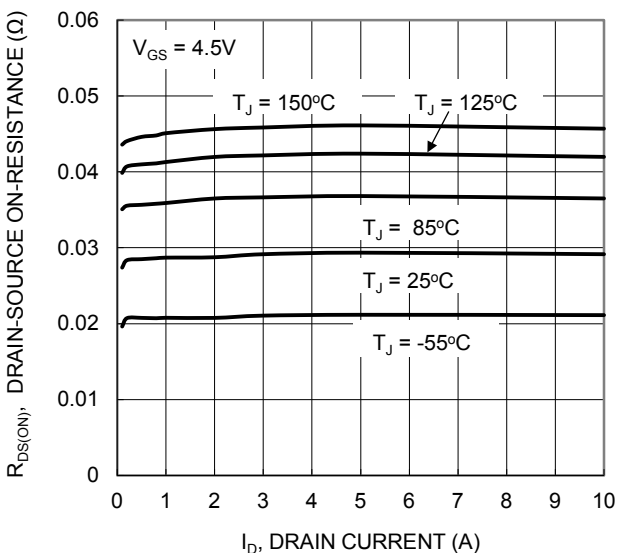


Figure 5. Typical On-Resistance vs Drain Current and Junction Temperature

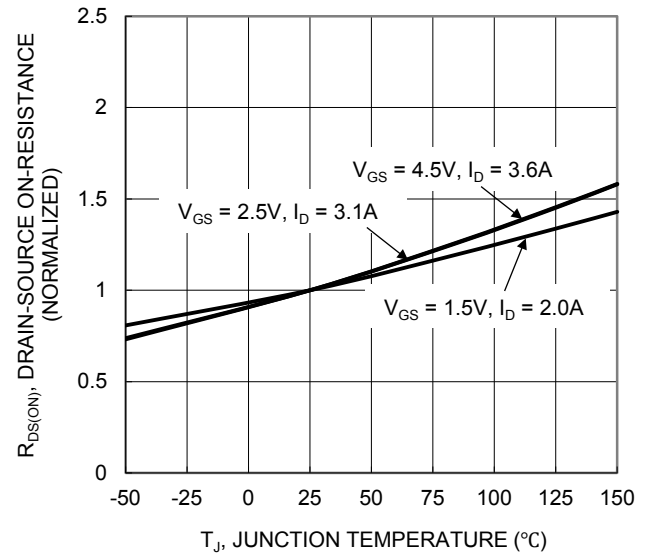
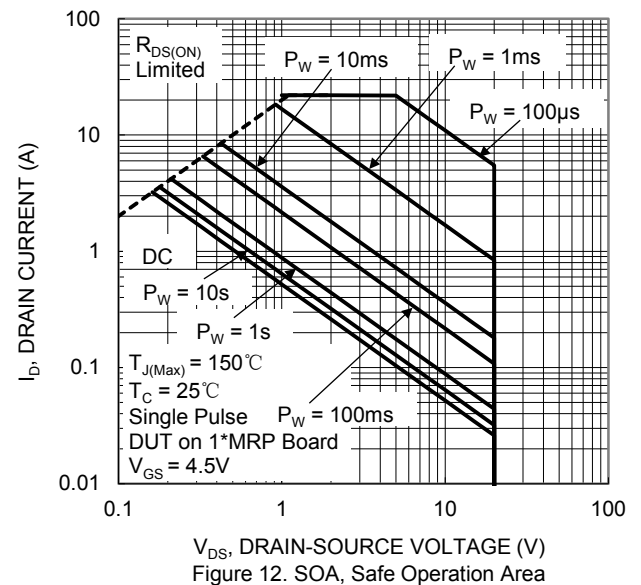
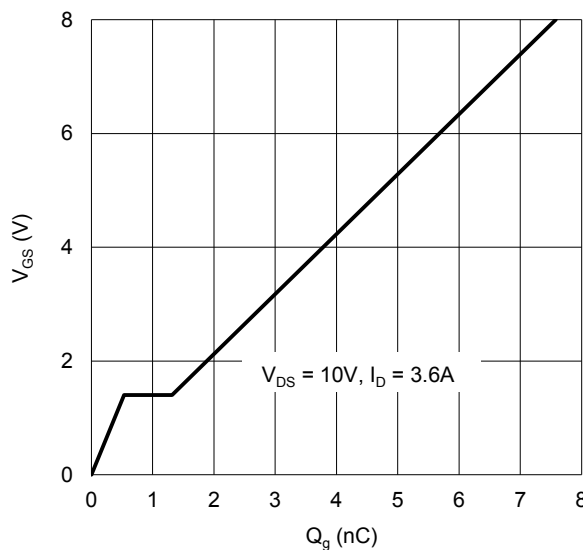
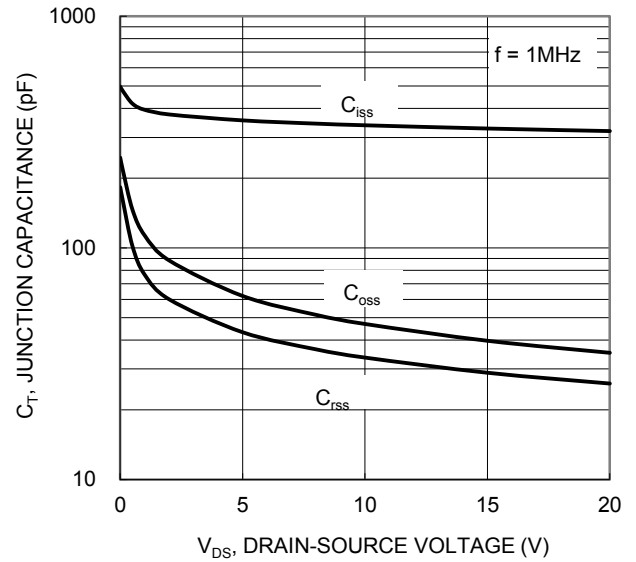
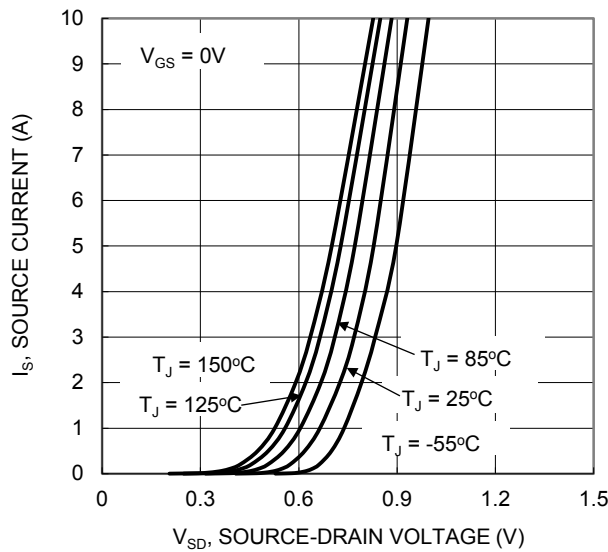
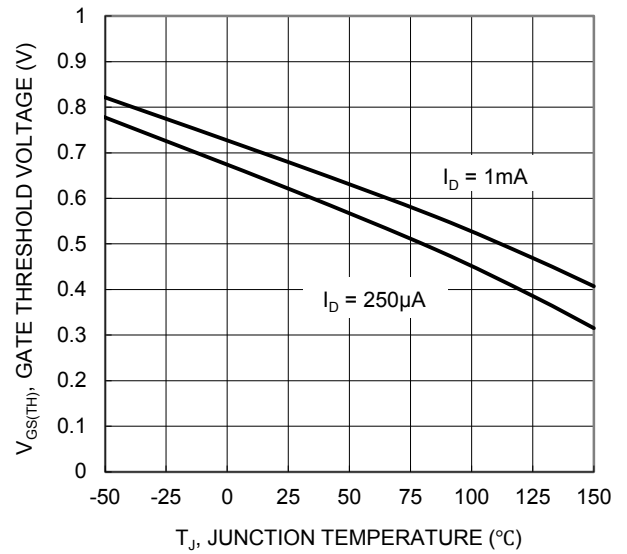
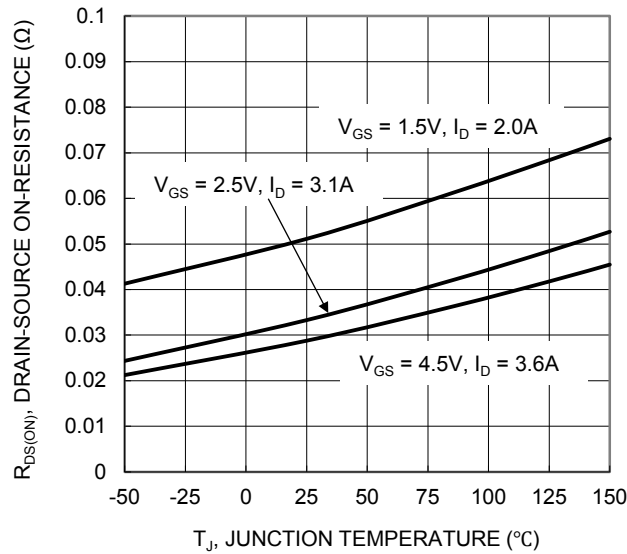


Figure 6. On-Resistance Variation with Junction Temperature



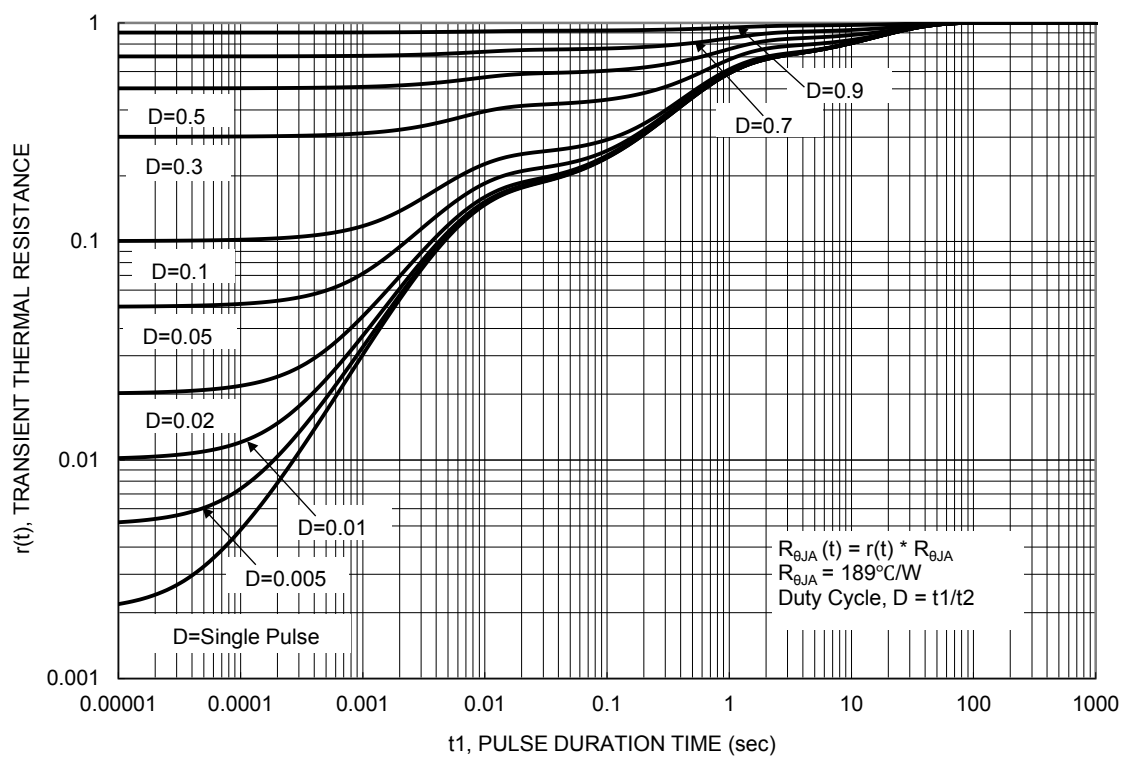
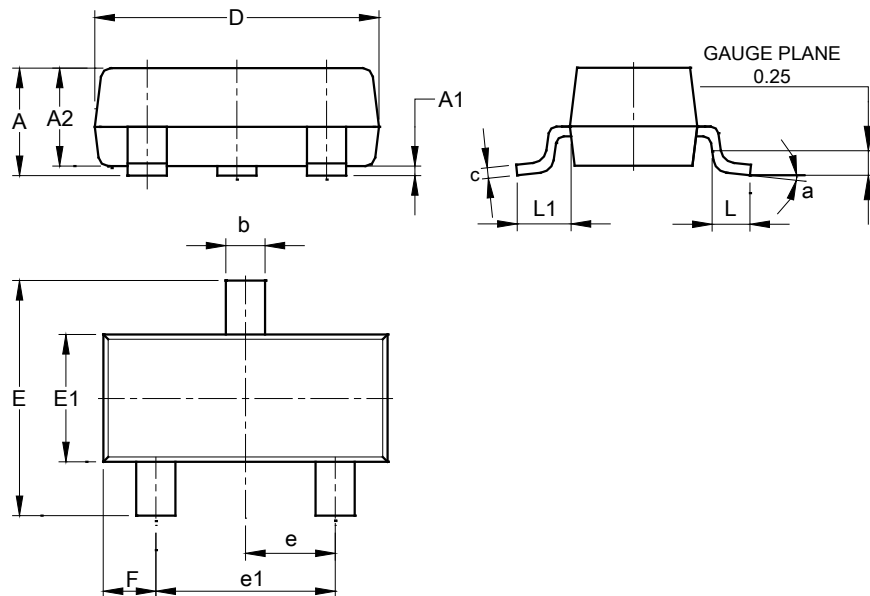


Figure 13. Transient Thermal Resistance

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23 (Standard)

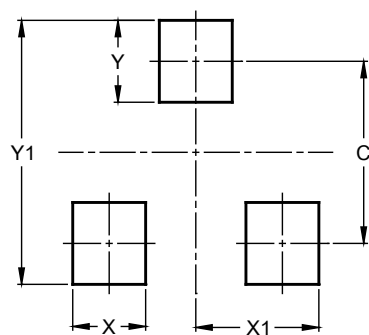


SOT23 (Standard)			
Dim	Min	Max	Typ
A	0.90	1.15	1.025
A1	0.00	0.10	0.05
A2	0.85	1.10	0.975
b	0.30	0.51	0.40
c	0.080	0.202	0.11
D	2.80	3.00	2.90
E	2.25	2.55	2.40
E1	1.20	1.40	1.30
e	0.89	1.03	0.915
e1	1.78	2.05	1.83
F	0.40	0.60	0.535
L1	0.45	0.61	0.55
L	0.25	0.55	0.40
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23 (Standard)



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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